

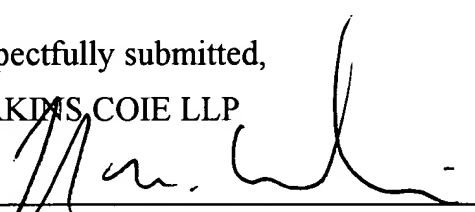
CROSS-REFERENCE TO RELATED APPLICATIONS

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This application is a continuation-in-part of U.S. Application No. 09/651,779, titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000. Additionally, this application is related to U.S. Application No. 09/888,084 (attorney docket number 108298515US1), titled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material From a Microelectronic Substrate," filed June 21, 2001, and U.S. Application No. 09/887,767 (attorney docket number 108298515US2), titled "Microelectronic Substrate Having Conductive Material With Blunt Cornered Apertures, and Associated Methods for Removing Conductive Material," filed June 21, 2001. All of the U.S. Patent Applications listed above are incorporated herein by reference.

REMARKS

Applicants respectfully request consideration of the application in view of this preliminary amendment. The enclosed Declaration reflects the priority claim, as corrected in this Preliminary Amendment. If the Examiner has any questions or matters that can be expediently handled by telephone, he or she is encouraged to contact Mr. Wechkin, attorney for the Applicants.

Respectfully submitted,
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**APPENDIX- SPECIFICATION
MARKED TO SHOW CHANGES**

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a continuation-in-part of U.S. Application No. 09/651,779 (~~attorney docket number 108298515US~~), titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000. Additionally, this application is related to, and U.S. Application No. 09/888,084 (attorney docket number 108298515US1), titled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material From a Microelectronic Substrate," filed June 21, 2001~~concurrently herewith,~~ and U.S. Application No. 09/887,767 (attorney docket number 108298515US2), titled "Microelectronic Substrate Having Conductive Material With Blunt Cornered Apertures, and Associated Methods for Removing Conductive Material," filed June 21, 2001~~concurrently herewith.~~ All of the U.S. Patent Applications listed above are incorporated herein by reference,~~all of which are incorporated herein in their entirety by reference.~~